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**Modular Jack, RJ45, With Shielded, DIP, Reverse version**

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**1. SCOPE**

## 1.1. Contents

This specification covers the performance, tests and quality requirements for the TE **Modular Jack, RJ45, With Shielded, DIP, Reverse version**.

## 1.2. Qualification

When tests are performed on the subject product line, procedures specified in Figure 1 shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

**2. APPLICABLE DOCUMENT**

The following TE documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

## 2.1. TE Documents

- 109-202: Component Heat Resistance to Wave Soldering.
- 501-57992: Qualification Test Report.

## 2.2. Commercial Standard

- EIA-364: Electrical Connector/Socket Test Procedures Including Environmental Classifications.
- MIL-STD-1344A: Test Methods for Electrical Connectors.
- JESD22-B102D: Solderability Test Method.

**3. REQUIREMENTS**

## 3.1. Design and Construction

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

## 3.2. Materials

Materials used in the construction of this product shall be as specified on the applicable product drawing.

## 3.3. Ratings

- A. Voltage: 150 volts AC.
- B. Current: 1 amperes.
- C. Temperature: -40 to 85°C.

## 3.4. Performance Requirement and Test Description

Product is designed to meet the electrical, mechanical and environmental performance requirements specified in Figure1. Unless otherwise specified, all tests shall be performed at ambient environmental conditions per EIA-364.

## 3.5 Test Requirements and Procedures Summary

| Test Description                  | Requirement  | Procedure   |
|-----------------------------------|--|---|
| Examination of product            | Meets requirements of product drawing.                                       | Visual and dimensional inspection per product drawing.  |
| ELECTRICAL                        |  |   |
| Contact Resistance                | 40m Ohm Max(Initial)<br>50m Ohm Max(Final)                                   | EIA-364-23<br>Subject specimens to 100 mA maximum and 20 mV maximum open circuit voltage.   |
| Dielectric withstanding Voltage   | 1 minute hold with no breakdown or flashover.                                | EIA-364-20<br>1000 VAC for 1minute<br>Test between adjacent circuits of unmated connector assemblies.   |
| Insulation Resistance             | 500 MΩ minimum initial.<br>200 MΩ minimum final.                             | EIA-364-21<br>After 500 VDC for 1 minute, measure the insulation resistance between the adjacent contacts of unmated connector assemblies.  |
| MECHANICAL                        |  |   |
| Vibration                         | No electrical discontinuity greater than 1μs or longer duration.<br>See note | EIA-364-28, Test condition VII, Test Condition Letter D.<br>Accelerate: 1.52mm.<br>Duration: 15 minutes in each of three mutually perpendicular.  |
| Mechanical shock                  | No electrical discontinuity greater than 1μs or longer duration.<br>See note | EIA-364-27, test condition A.<br>Subject mated specimens to 50 G's half-sine shock pulses of 11 milliseconds duration. 3 shocks in each direction applied along 3 mutually perpendicular planes, 18 total shocks. |
| Mating Force                      | 2.3 Kgf maximum.   | EIA-364-13C, method A<br>Measure force necessary to mate the connector assemblies at a max 25 mm/minute.  |
| Durability                        | See Note   | EIA-364-09<br>Mate and Unmated connector assemblies for 750 cycles at a maximum rate of 25 mm/minute.   |
| Solderability                     | The inspected area of each lead must have 95% solder coverage minimum.       | JESD22-B102D, Condition C<br>Steam Aging Preconditioning: 93 +3/-5°C, 8 hours ±15 min. Solder Temperature: 245 ±5°C. Solder Immersion Time: 5 ±0.5 s.   |
| Un-mating Force (W/ Locked)       | 7 Kgf minimum.   | Measure force necessary to un-mate the connector assemblies at max 25 mm/min.   |
| ENVIRONMENTAL                     |  |   |
| Resistance to wave Soldering Heat | See Note.  | Solder Temp. : 265±5°C, 10+2/-0sec.<br>Test spec. 109-202, Condition B  |
| Temperature Life                  | See Note   | EIA-364-17 test condition 3, method B.<br>Subject Mated Connector to 85 ±2°C, for 250 hours   |

Figure 1 (continued)

|            |                       |  |
|------------|-----------------------|--|
| Humidity   | See Note              | MIL-STD-1344A, Method 1002.2, type 1 condition B.<br>At a temperature of 40 ±2°C and relative humidity of 90 ~ 95% for 96 hours.   |
| Salt Spray | No evident corrosion. | EIA-364-26<br>Subject mated connectors to 35+/-2°C and 5+/-1% salt condition for 48hours. After test, rinse the sample with water and recondition the room temperature for 1 hour. |

**NOTE** Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Requalification Test Sequence shown in Figure 2.

Figure 1 (end)

### 3.5. Product Qualification and Requalification Test Sequence

| Test or Examination               | Test Group        |      |      |      |      |      |      |      |
|-----------------------------------|-------------------|------|------|------|------|------|------|------|
|                                   | A                 | B    | C    | D    | E    | F    | G    | H    |
|                                   | Test Sequence (a) |      |      |      |      |      |      |      |
| Examination of product.           | 1, 7              | 1, 7 | 1, 5 | 1, 5 | 1, 3 | 1, 4 | 1, 5 | 1, 7 |
| Contact Resistance                |                   | 2, 6 | 2, 4 | 2, 4 |      |      | 2, 4 | 3, 6 |
| Dielectric withstanding Voltage   | 3, 6              |      |      |      |      |      |      |      |
| Insulation Resistance             | 2, 5              |      |      |      |      |      |      |      |
| Vibration                         |                   |      |      |      |      |      |      | 4    |
| Mechanical shock                  |                   |      |      |      |      |      |      | 5    |
| Mating Force                      |                   | 3, 5 |      |      |      |      |      | 2    |
| Durability                        | 4                 | 4    |      |      |      |      |      |      |
| Solderability                     |                   |      |      |      |      | 2    |      |      |
| Un-mating Force (W/ Locked)       |                   |      |      |      |      | 3    |      |      |
| Resistance to wave Soldering Heat |                   |      |      |      | 2    |      |      |      |
| Temperature Life                  |                   |      | 3    |      |      |      |      |      |
| Humidity Test                     |                   |      |      |      |      |      | 3    |      |
| Salt Spray                        |                   |      |      | 3    |      |      |      |      |

**NOTE** (a) Numbers indicate sequence in which test are performed.

Figure 2